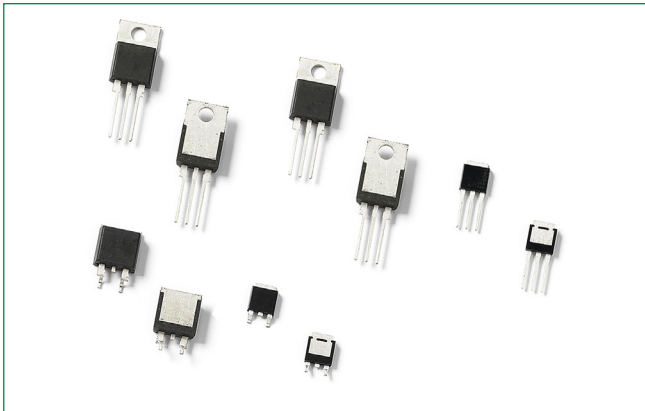




Sxx10xSx & Sxx10x Series



**Main Features**

Symbol	Value	Unit
$I_{T(RMS)}$	10	A
$V_{DRM}/V_{RRM}$	400 to 1000	V
$I_{GT}$	0.2 to 15	mA

**Additional Information**



Datasheet



Resources



Samples

**Description**

This Sxx10x SCR series is ideal for uni-directional switch applications such as phase control, heating, motor speed controls, converters/rectifiers and capacitive discharge ignitions.

These SCRs have a low gate current trigger level of 0.2 to 15 mA at approximately 1.5V, with a sensitive version of this series having a gate trigger current less than 500µA. The sensitive gate SCR version is easily triggered by sense coils, proximity switches, and microprocessors.

**Features & Benefits**

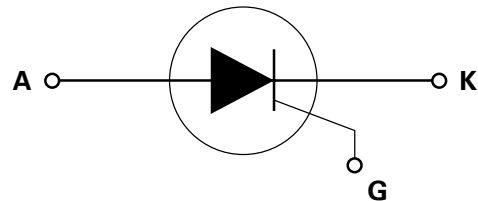
- Halogen-free and RoHS-compliant
- Glass – passivated junctions
- Voltage capability up to 1000 V
- Surge capability up to 100 A at 60 Hz half cycle

**Applications**

Typical applications includes capacitive discharge system for motorcycle engine CDI, portable generator engine ignition, strobe lights and nailers, as well as generic rectifiers, battery voltage regulators and converters. Also AC control & rectification for power tools, home/brown goods, white goods appliances and 2-wheeler rectifier/battery regulators.

Internally constructed isolated packages are offered for ease of heat sinking with highest isolation voltage.

**Schematic Symbol**



### Absolute Maximum Ratings — Sensitive SCRs

Symbol	Parameter	Test Conditions		Value	Unit
$I_{T(RMS)}$	RMS on-state current	Sxx10LSy	$T_c = 80^\circ\text{C}$	10	A
		Sxx10RSy / Sxx10NSy Sxx10DSy Sxx10VSy	$T_c = 95^\circ\text{C}$		
$I_{T(AV)}$	Average on-state current	Sxx10LSy	$T_c = 80^\circ\text{C}$	6.4	A
		Sxx10RSy / Sxx10NSy Sxx10DSy Sxx10VSy	$T_c = 95^\circ\text{C}$		
$I_{TSM}$	Peak non-repetitive surge current	single half cycle; f = 50Hz; $T_J$ (initial) = $25^\circ\text{C}$		83	A
		single half cycle; f = 60Hz; $T_J$ (initial) = $25^\circ\text{C}$		100	
$I^2t$	$I^2t$ Value for fusing	$t_p = 8.3$ ms		41	$\text{A}^2\text{s}$
$di/dt$	Critical rate of rise of on-state current	f = 60 Hz ; $T_J = 110^\circ\text{C}$		100	$\text{A}/\mu\text{s}$
$I_{GM}$	Peak gate current	$T_J = 110^\circ\text{C}$		1	A
$P_{G(AV)}$	Average gate power dissipation	$T_J = 110^\circ\text{C}$		0.1	W
$T_{stg}$	Storage temperature range			-40 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range			-40 to 110	$^\circ\text{C}$

Note: xx = voltage, y = sensitivity

### Absolute Maximum Ratings — Standard SCRs

Symbol	Parameter	Test Conditions		Value	Unit
$I_{T(RMS)}$	RMS on-state current	Sxx10L	$T_c = 95^\circ\text{C}$	10	A
		Sxx10R / Sxx10N Sxx10D Sxx10V	$T_c = 105^\circ\text{C}$		
$I_{T(AV)}$	Average on-state current	Sxx10L	$T_c = 95^\circ\text{C}$	6.4	A
		Sxx10R / Sxx10N Sxx10D Sxx10V	$T_c = 105^\circ\text{C}$		
$I_{TSM}$	Peak non-repetitive surge current	single half cycle; f = 50Hz; $T_J$ (initial) = $25^\circ\text{C}$		83	A
		single half cycle; f = 60Hz; $T_J$ (initial) = $25^\circ\text{C}$		100	
$I^2t$	$I^2t$ Value for fusing	$t_p = 8.3$ ms		41	$\text{A}^2\text{s}$
$di/dt$	Critical rate-of-rise of on-state current	f = 60 Hz $T_J = 125^\circ\text{C}$		100	$\text{A}/\mu\text{s}$
$I_{GM}$	Peak gate current	$T_J = 125^\circ\text{C}$		2	A
$P_{G(AV)}$	Average gate power dissipation	$T_J = 125^\circ\text{C}$		0.5	W
$T_{stg}$	Storage temperature range			-40 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range			-40 to 125	$^\circ\text{C}$

Note: xx = voltage

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise specified) – Sensitive SCRs

Symbol	Test Conditions		Value		Unit
			Sxx10xS2	Sxx10xS3	
$I_{GT}$	$V_D = 6V$ $R_L = 100\ \Omega$	MAX.	200	500	$\mu\text{A}$
$V_{GT}$	$V_D = 6V$ $R_L = 100\ \Omega$	MAX.	0.8		V
dv/dt	$V_D = V_{DRM}$ ; $R_{GK} = 1k\ \Omega$ ; $T_J = 110^\circ\text{C}$	TYP.	8		V/ $\mu\text{s}$
$V_{GD}$	$V_D = V_{DRM}$ ; $R_L = 3.3\ k\ \Omega$ ; $T_J = 110^\circ\text{C}$	MIN.	0.2		V
$V_{GRM}$	$I_{GR} = 10\ \mu\text{A}$	MIN.	6		V
$I_H$	$I_T = 20\text{mA}$ (initial)	MAX.	6	8	mA
$t_q$	(1)	MAX.	50	45	$\mu\text{s}$
$t_{gt}$	$I_G = 2 \times I_{GT}$ ; $PW = 15\ \mu\text{s}$ ; $I_T = 12\text{A}$	TYP.	4	5	$\mu\text{s}$

Note: xx = voltage, x = package  
 (1)  $I_T = 2\text{A}$ ;  $t_p = 50\ \mu\text{s}$ ;  $dv/dt = 5\text{V}/\mu\text{s}$ ;  $di/dt = 30\text{A}/\mu\text{s}$

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise specified) – Standard SCRs

Symbol	Test Conditions			Value	Unit
				Sxx10x	
$I_{GT}$	$V_D = 12V$ $R_L = 60\ \Omega$	-	MAX.	15	mA
$V_{GT}$	$V_D = 12V$ $R_L = 60\ \Omega$	-	MAX.	1.5	V
dv/dt	$V_D = V_{DRM}$ ; gate open; $T_J = 100^\circ\text{C}$	400V	MIN.	350	V/ $\mu\text{s}$
		600V		300	
		800V		250	
	$V_D = V_{DRM}$ ; gate open; $T_J = 125^\circ\text{C}$	1000V		100	
		400V		250	
		600V		225	
$V_{GD}$	$V_D = V_{DRM}$ ; $R_L = 3.3\ k\ \Omega$ ; $T_J = 125^\circ\text{C}$	-	MIN.	0.2	V
$I_H$	$I_T = 200\text{mA}$ (initial)	-	MAX.	30	mA
$t_q$	(1)	-	MAX.	35	$\mu\text{s}$
$t_{gt}$	$I_G = 2 \times I_{GT}$ ; $PW = 15\ \mu\text{s}$ ; $I_T = 20\text{A}$	-	TYP.	2	$\mu\text{s}$

Note: xx = voltage, x = package  
 (1)  $I_T = 2\text{A}$ ;  $t_p = 50\ \mu\text{s}$ ;  $dv/dt = 5\text{V}/\mu\text{s}$ ;  $di/dt = 30\text{A}/\mu\text{s}$

### Static Characteristics

Symbol	Test Conditions		Value	Unit	
$V_{TM}$	$I_T = 20\text{A}$ ; $t_p = 380\ \mu\text{s}$		MAX.	1.6	
$I_{DRM} / I_{RRM}$	Sxx10xyy	$T_J = 25^\circ\text{C}$	400 - 600V	5	$\mu\text{A}$
		$T_J = 110^\circ\text{C}$	400 - 600V	250	
	Sxx10x	$T_J = 25^\circ\text{C}$	400 - 800V	10	
			1000V	20	
		$T_J = 100^\circ\text{C}$	400 - 800V	200	
			1000V	3000	
		$T_J = 125^\circ\text{C}$	400 - 800V	500	

Note: xx = voltage, x = package, yy = sensitivity

**Thermal Resistances**

Symbol	Parameter	Value	Unit	
$R_{\theta(J-C)}$	Junction to case (AC)	Sxx10RSy / Sxx10NSy	1.6	°C/W
		Sxx10LSy	3.0	
		Sxx10VSY	1.7	
		Sxx10DSy	1.45	
		Sxx10R / Sxx10N	1.6	
		Sxx10L	3.0	
		Sxx10V	1.7	
		Sxx10D	1.45	
$R_{\theta(J-A)}$	Junction to ambient	Sxx10RSy	40	°C/W
		Sxx10LSy	65	
		Sxx10VSY	85	
		Sxx10R	40	
		Sxx10L	50	
		Sxx10V	70	

Note: xx = voltage, y = sensitivity

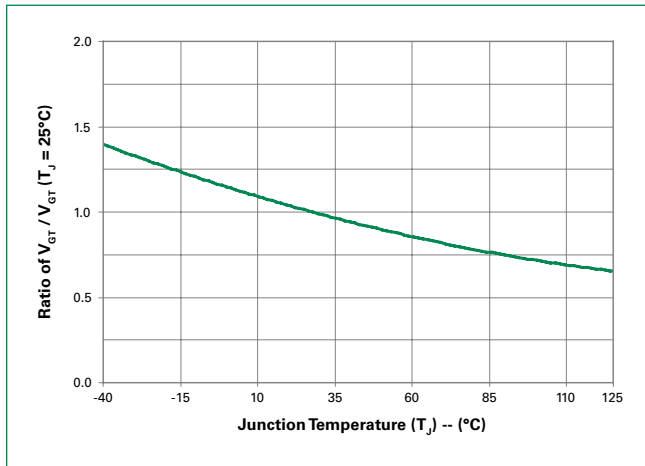
**Figure 1: Normalized DC Gate Trigger Current vs. Junction Temperature (Sensitive SCR)**



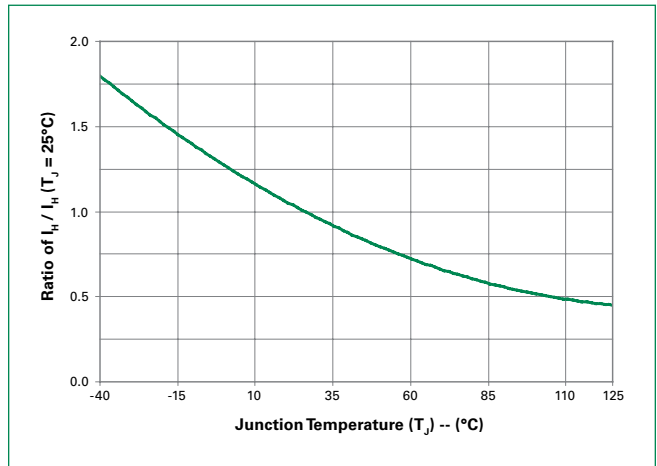
**Figure 2: Normalized DC Gate Trigger Current vs. Junction Temperature (Standard SCR)**



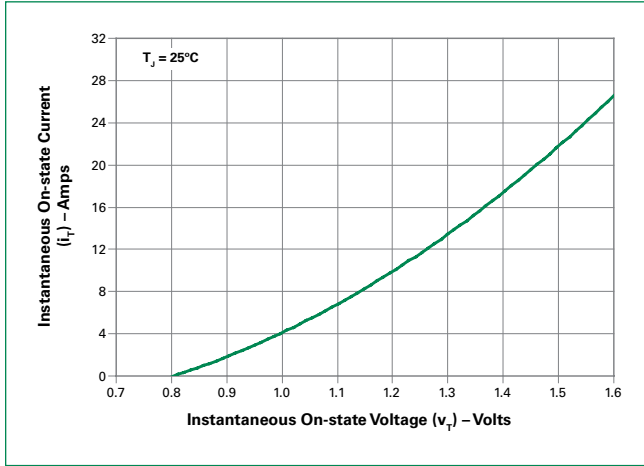
**Figure 3: Normalized DC Gate Trigger Voltage vs. Junction Temperature**



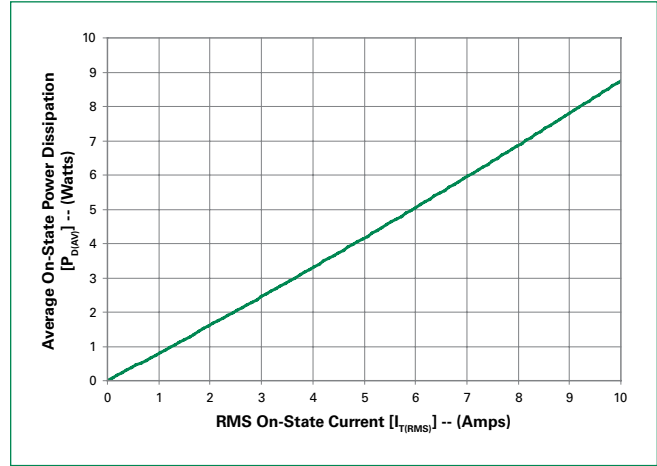
**Figure 4: Normalized DC Holding Current vs. Junction Temperature**



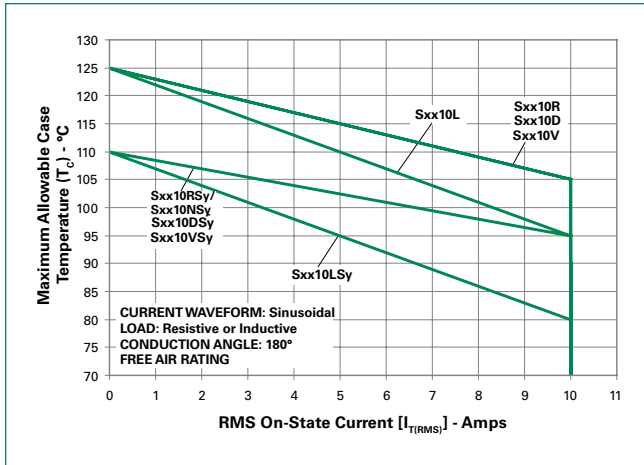
**Figure 5: On-State Current vs. On-State Voltage (Typical)**



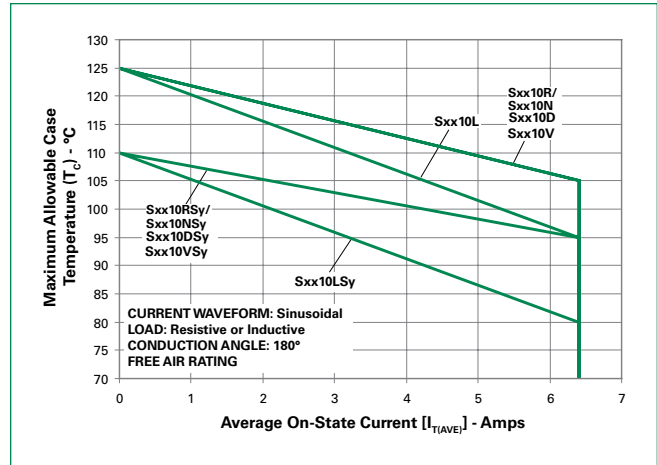
**Figure 6: Power Dissipation (Typical) vs. RMS On-State Current**



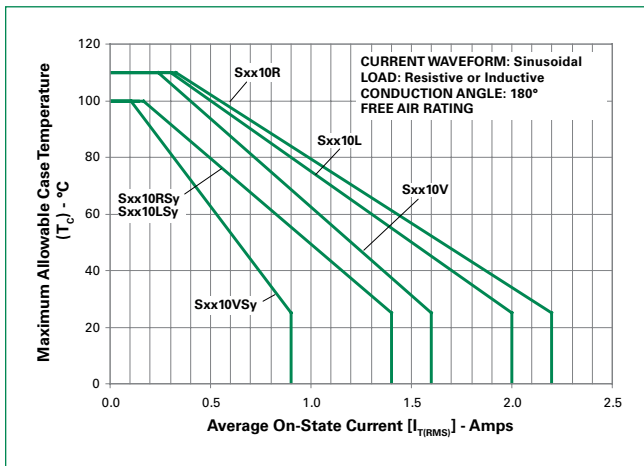
**Figure 7: Maximum Allowable Case Temperature vs. RMS On-State Current**



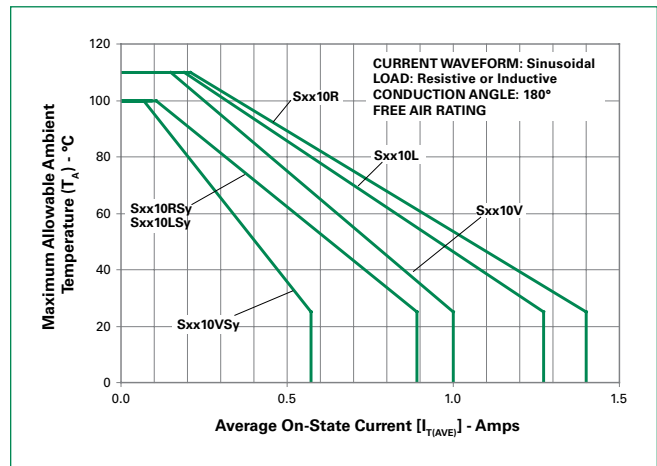
**Figure 8: Maximum Allowable Case Temperature vs. Average On-State Current**



**Figure 9: Maximum Allowable Ambient Temperature vs. RMS On-State Current**



**Figure 10: Maximum Allowable Ambient Temperature vs. Average On-State Current**



Note: xx = voltage, y = sensitivity

**Figure 11: Peak Capacitor Discharge Current**



**Figure 12: Peak Capacitor Discharge Current Derating**



**Figure 13-1: Typical DC Holding Current with  $R_{GK}$  vs. Junction Temperature for S60010xS2**



**Figure 13-1: Typical DC Holding Current with  $R_{GK}$  vs. Junction Temperature for S60010xS3**



**Figure 14-1: Typical DC Holding Current with  $R_{GK}$  vs. Junction Temperature for S60010xS2**



**Figure 14-2: Typical DC Holding Current with  $R_{GK}$  vs. Junction Temperature for S60010xS3**



**Figure 15-1: Typical Static dv/dt with  $R_{GK}$  vs. Junction Temperature for S60010xS2**



**Figure 15-2: Typical Static dv/dt with  $R_{GK}$  vs. Junction Temperature for S60010xS3**



**Figure 16-1: Typical turn off time with  $R_{GK}$  vs. Junction Temperature for S60010xS2**



**Figure 16-2: Typical DC Gate Trigger Current with  $R_{GK}$  vs. Junction Temperature for S60010xS3**

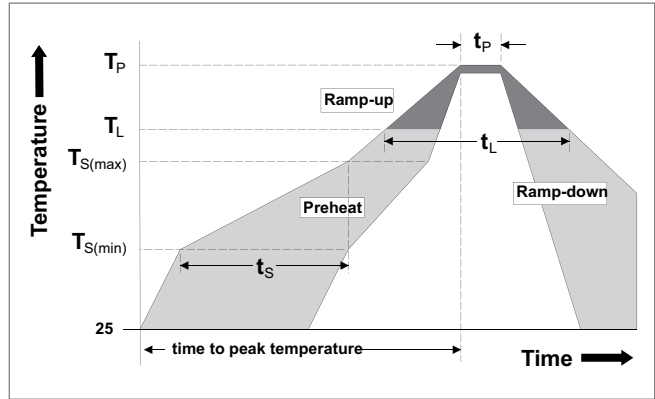


**Figure 17: Surge Peak On-State Current vs. Number of Cycles**



**Soldering Parameters**

<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
<b>Average ramp up rate (Liquidus Temp) (<math>T_L</math>) to peak</b>		5°C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		5°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		20 – 40 seconds
<b>Ramp-down Rate</b>		5°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		280°C



**Physical Specifications**

<b>Terminal Finish</b>	100% Matte Tin-plated
<b>Body Material</b>	UL Recognized epoxy meeting flammability rating 94V-0
<b>Lead Material</b>	Copper Alloy

**Design Considerations**

Careful selection of the correct component for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the component rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

**Environmental Specifications**

Test	Specifications and Conditions
<b>AC Blocking</b>	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 125°C for 1008 hours
<b>Temperature Cycling</b>	MIL-STD-750, M-1051, 100 cycles; -40°C to +150°C; 15-min dwell-time
<b>Temperature/Humidity</b>	EIA / JEDEC, JESD22-A101 1008 hours; 320V - DC: 85°C; 85% rel humidity
<b>High Temp Storage</b>	MIL-STD-750, M-1031, 1008 hours; 150°C
<b>Low-Temp Storage</b>	1008 hours; -40°C
<b>Resistance to Solder Heat</b>	MIL-STD-750 Method 2031
<b>Solderability</b>	ANSI/J-STD-002, category 3, Test A
<b>Lead Bend</b>	MIL-STD-750, M-2036 Cond E

**Product Selector**

Part Number	Voltage				Gate Sensitivity	Type	Package
	400V	600V	800V	1000V			
Sxx10RS2	X	X	-	-	0.2mA	Sensitive SCR	TO-220R
Sxx10LS2	X	X	-	-	0.2mA	Sensitive SCR	TO-220L
Sxx10VS2	X	X	-	-	0.2mA	Sensitive SCR	TO-251
Sxx10DS2	X	X	-	-	0.2mA	Sensitive SCR	TO-252
Sxx10RS3	X	X	-	-	0.5mA	Sensitive SCR	TO-220R
Sxx10LS3	X	X	-	-	0.5mA	Sensitive SCR	TO-220L
Sxx10VS3	X	X	-	-	0.5mA	Sensitive SCR	TO-251
Sxx10DS3	X	X	-	-	0.5mA	Sensitive SCR	TO-252
Sxx10R	X	X	X	X	15mA	Standard SCR	TO-220R
Sxx10L	X	X	X	X	15mA	Standard SCR	TO-220L
Sxx10V	X	X	X	X	15mA	Standard SCR	TO-251
Sxx10D	X	X	X	X	15mA	Standard SCR	TO-252
Sxx10NS2	X	X	-	-	15mA	Sensitive SCR	TO-263
Sxx10NS3	X	X	-	-	15mA	Sensitive SCR	TO-263
Sxx10N	X	X	X	X	15mA	Standard SCR	TO-263

Note: xx = Voltage/10

**Dimensions – TO-251AA (V/I-Package) – V/I-PAK Through Hole**



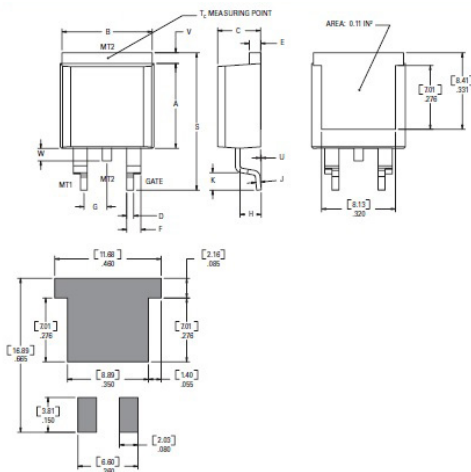
Dimension	Inches			Millimeters		
	Min	Typ	Max	Min	Typ	Max
A	0.037	0.040	0.043	0.94	1.01	1.09
B	0.235	0.242	0.245	5.97	6.15	6.22
C	0.350	0.361	0.375	8.89	9.18	9.53
D	0.205	0.208	0.213	5.21	5.29	5.41
E	0.255	0.262	0.265	6.48	6.66	6.73
F	0.027	0.031	0.033	0.69	0.80	0.84
G	0.087	0.090	0.093	2.21	2.28	2.36
H	0.085	0.092	0.095	2.16	2.34	2.41
I	0.176	0.180	0.184	4.47	4.57	4.67
J	0.018	0.020	0.023	0.46	0.51	0.58
K	0.035	0.037	0.039	0.90	0.95	1.00
L	0.018	0.020	0.023	0.46	0.52	0.58
P	0.042	0.047	0.052	1.06	1.20	1.32
Q	0.034	0.039	0.044	0.86	1.00	1.11
R	0.034	0.039	0.044	0.86	1.00	1.11
S	0.074	0.079	0.084	1.86	2.00	2.11

### Dimensions — TO-252AA (D-Package) — D-PAK Surface Mount



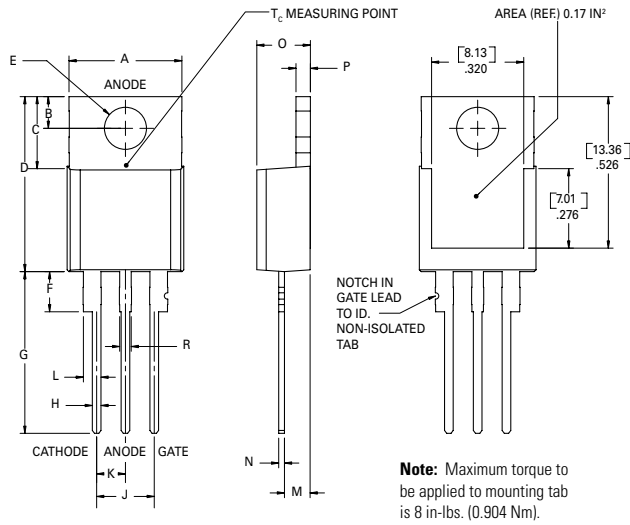
Dimension	Inches			Millimeters		
	Min	Typ	Max	Min	Typ	Max
A	0.037	0.040	0.043	0.94	1.01	1.09
B	0.235	0.243	0.245	5.97	6.16	6.22
C	0.106	0.108	0.113	2.69	2.74	2.87
D	0.205	0.208	0.213	5.21	5.29	5.41
E	0.255	0.262	0.265	6.48	6.65	6.73
F	0.027	0.031	0.033	0.69	0.80	0.84
G	0.087	0.090	0.093	2.21	2.28	2.36
H	0.085	0.092	0.095	2.16	2.33	2.41
I	0.176	0.179	0.184	4.47	4.55	4.67
J	0.018	0.020	0.023	0.46	0.51	0.58
K	0.035	0.037	0.039	0.90	0.95	1.00
L	0.018	0.020	0.023	0.46	0.51	0.58
M	0.000	0.000	0.004	0.00	0.00	0.10
N	0.021	0.026	0.027	0.53	0.67	0.69
O	0°	0°	5°	0°	0°	5°
P	0.042	0.047	0.052	1.06	1.20	1.32
Q	0.034	0.039	0.044	0.86	1.00	1.11

### Dimensions — TO-263 (N-Package) — D²PAK Surface Mount



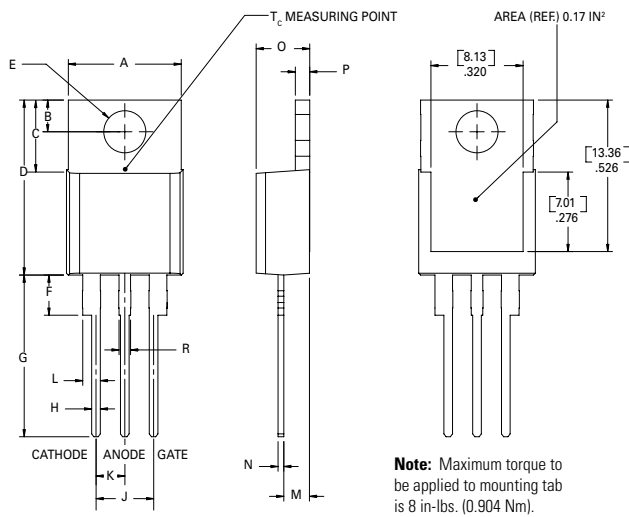
Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.370	9.14	9.40
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
E	0.045	0.060	1.14	1.52
F	0.060	0.075	1.52	1.91
G	0.095	0.105	2.41	2.67
H	0.092	0.102	2.34	2.59
J	0.018	0.024	0.46	0.61
K	0.090	0.110	2.29	2.79
S	0.590	0.625	14.99	15.88
V	0.035	0.045	0.89	1.14
U	0.002	0.010	0.05	0.25
W	0.040	0.070	1.02	1.78

### Dimensions — TO-220AB (R-Package) — Non-Isolated Mounting Tab Common with Center Lead



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

### Dimensions — TO-220AB (L-Package) — Isolated Mounting Tab



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

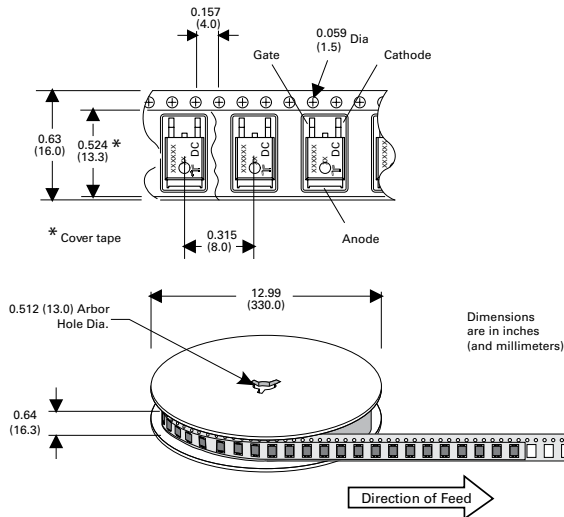
### Packing Options

Part Number	Marking	Weight	Packing Mode	Base Quantity
Sxx10L/RyyTP	Sxx10L/Ryy	2.2 g	Tube	1000 (50 per tube)
Sxx10DyyTP	Sxx10Dyy	0.3 g	Tube	750 (75 per tube)
Sxx10DyyRP	Sxx10Dyy	0.3 g	Embossed Carrier	2500
Sxx10VyyTP	Sxx10Vyy	0.4 g	Tube	750 (75 per tube)
Sxx10L/RTP	Sxx10L/R	2.2 g	Tube	1000 (50 per tube)
Sxx10DTP	Sxx10D	0.3 g	Tube	750 (75 per tube)
Sxx10DRP	Sxx10D	0.3 g	Embossed Carrier	2500
Sxx10VTP	Sxx10V	0.4 g	Tube	750 (75 per tube)
Sxx10NSyTP	Sxx10NSy	1.6 g	Tube	1000 (50 per tube)
Sxx10NSyRP	Sxx10NSy	1.6 g	Embossed Carrier	500
Sxx10NTP	Sxx10N	1.6 g	Tube	1000 (50 per tube)
Sxx10NRP	Sxx10N	1.6 g	Embossed Carrier	500

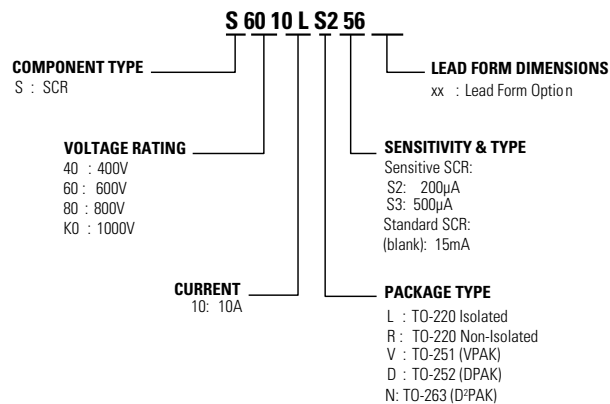
Note: xx = Voltage/10; yy = Sensitivity

### TO-252 Embossed Carrier Reel Pack (RP) Specifications

Meets all EIA-481-2 Standards

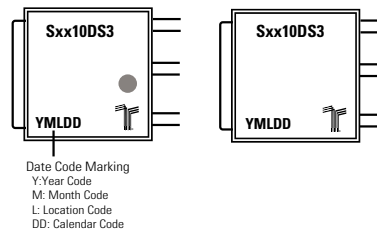


### Part Numbering System



### Part Marking System

TO-251AA - (V Package)  
TO-252AA - (D Package)



TO-263 AA - (N Package)  
TO-220 AB - (L and R Package)



**Disclaimer Notice** - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at <http://www.littelfuse.com/disclaimer-electronics>.

## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View S4010R on WIN SOURCE](#)

 [Littelfuse Inc. Information](#)

## Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management